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Product Highlights:

- Heat Sink
- BGA
- Package Size = 42.5 [1.675] mm [in]
- For Use With BGA Semiconductor Packages
- Power Air Velocity Thermal Resistance

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Product Drawings: • 42.5mm HS ASSEMBLY (HTS573-U) (PDF, English)	Additional Information: • Product Line Information
Catalog Pages/Data Sheets: • None Available	Additional Product Images: • Line Drawing • Thermal Resistance Chart
Product Specifications: • None Available	Related Products: • Tooling
Application Specifications: • None Available	
Instruction Sheets: • None Available	
CAD Files: • None Available	
List all Documents	

Product Type Features: • Product Type = Heat Sink • Device Type = BGA • For Use With = BGA Semiconductor Packages • Finish = Black Anodize • Material = Aluminum • Comment = Mounting clip does not increase overall heat sink height.; Heat sink assembly includes Four Leg Standard Clip, Part Number 1542361-1. Electrical Characteristics: • Heat Sink Type = 5 Fin Radial Termination Related Features: • Height (mm [in]) = 17.22 [0.678]	Body Related Features: • Package Size (mm [in]) = 42.5 [1.675] • Flammability Rating = UL 94V-0 Configuration Related Features: • Diameter (mm [in]) = 50.80 [2.000] Industry Standards: • RoHS/ELV Compliance = RoHS compliant, ELV compliant • Lead Free Solder Processes = Not relevant for lead free process • RoHS/ELV Compliance History = Always was RoHS compliant Other: • Brand = Tyco Electronics • Line = ChipCoolers
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When Power (W) is:	And Air Velocity is:	Thermal Resistance (°C) is:
5.0	0 LFM	8.73
5.0	200 LFM	3.30
5.0	400 LFM	1.84
5.0	600 LFM	1.95
10.0	0 LFM	7.69
10.0	200 LFM	3.23
10.0	400 LFM	1.92
10.0	600 LFM	1.59
15.0	0 LFM	7.13
15.0	200 LFM	3.21
15.0	400 LFM	1.96
15.0	600 LFM	1.71